



# Working Instructions, HVC/Electrical Repair

Applicable for Z200, Z208

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# 1 Replacement of parts

## 1.1 IrDA (U8)

### 1.1.1 Process Tools

- Pair of tweezers.
- Hot air soldering equipment
- De-soldering braid
- Soldering paste.

### 1.1.2 Equipment

- ESD-gloves (cotton gloves)
- ESD-wristband

### 1.1.3 Instructions

Disassemble the phone as described in Working Instructions, SP/Mechanical.

(1. Disassembly)

Remove the IrDA with hot air soldering equipment.

Remove old residual of soldering paste on the PCB.

Mount the new component with hot air soldering equipment

Assemble the phone as described in Working Instructions, SP/Mechanical.

(2. Reassembly)

## 1.2 Hall Sensor (U9)

### 1.2.1 Process Tools

- Pair of tweezers.
- Hot air soldering equipment
- De-soldering braid
- Soldering paste.



### 1.2.2 Equipment

- ESD-gloves (cotton gloves)
- ESD-wristband

### 1.2.3 Instructions

Disassemble the phone as described in Working Instructions, SP/Mechanical.

(1. Disassembly)

Remove the Hall Sensor with hot air soldering equipment.

Remove old residual of soldering paste on the PCB.

Mount the new component with hot air soldering equipment

Assemble the phone as described in Working Instructions, SP/Mechanical.

(2. Reassembly)

## 1.3 Keypad Led

### 1.3.1 Process Tools

- Pair of tweezers.
- Soldering iron
- De-soldering braid
- Soldering paste

### 1.3.2 Equipment

- ESD-gloves (cotton gloves)
- ESD-wristband

### 1.3.3 Instructions

Disassemble the phone as described in Working Instructions, SP/Mechanical.

(1. Disassembly)

Remove the defective Keypad Led with a soldering iron.

Remove old residual of soldering paste on the PCB.

Mount the new component with a soldering iron.

Assemble the phone as described in Working Instructions, SP/Mechanical.

(2. Reassembly)



## 1.4 Sidekey PCB

### 1.4.1 Process Tools

- Pair of tweezers.
- Soldering iron
- De-soldering braid
- Soldering Paste.

### 1.4.2 Equipment

- ESD-gloves (cotton gloves)
- ESD-wristband

### 1.4.3 Instructions

Disassemble the phone as described in Working Instructions, SP/Mechanical.

(1. Disassembly)

Remove the defective Sidekey PCB with a soldering iron,

Remove old residual of soldering paste on the PCB.

Mount the new component with a soldering iron.

**Note. If too much soldering paste is used, it might cause poor feeling in key 4 and 7.**

Assemble the phone as described in Working Instructions, SP/Mechanical.

(2. Reassembly)

## 1.5 L1, L7, C71

### 1.5.1 Process Tools

- Pair of tweezers.
- Hot air soldering equipment
- Soldering iron
- De-soldering braid
- Soldering paste.

### 1.5.2 Equipment

- ESD-gloves (cotton gloves)
- ESD-wristband



### 1.5.3 Instructions

Disassemble the phone as described in Working Instructions, SP/Mechanical.

(1. Disassembly)

Remove the defective component with hot air soldering equipment.

Remove old residual of soldering paste on the PCB.

Mount the new component with hot air soldering equipment

Assemble the phone as described in Working Instructions, SP/Mechanical.

(2. Reassembly)

## 1.6 R29, D8, D22

### 1.6.1 Process Tools

- Pair of tweezers.
- Hot air soldering equipment
- Soldering iron
- De-soldering braid
- Soldering paste.

### 1.6.2 Equipment

- ESD-gloves (cotton gloves)
- ESD-wristband

### 1.6.3 Instructions

Disassemble the phone as described in Working Instructions, SP/Mechanical.

(1. Disassembly)

Remove the defective component with hot air soldering equipment.

Remove old residual of soldering paste on the PCB.

Mount the new component with hot air soldering equipment

Assemble the phone as described in Working Instructions, SP/Mechanical.

(2. Reassembly)



## 1.7 Q3 Transistor

### 1.7.1 Process Tools

- Pair of tweezers.
- Hot air soldering equipment
- Soldering iron
- De-soldering braid
- Soldering paste.

### 1.7.2 Equipment

- ESD-gloves (cotton gloves)
- ESD-wristband

### 1.7.3 Instructions

Disassemble the phone as described in Working Instructions, SP/Mechanical.

(2. Disassembly)

Remove the defective component with hot air soldering equipment.

Remove old residual of soldering paste on the PCB.

Mount the new component with hot air soldering equipment

Assemble the phone as described in Working Instructions, SP/Mechanical.

(2. Reassembly)



## **1.8 Other components in the Electrical Spare Part List**

Use standard repair procedure to replace the components.

### **1.8.1 Process Tools**

- Pair of tweezers.
- Hot air
- Soldering iron
- De-soldering braid
- Soldering paste.

### **1.8.2 Equipment**

- ESD-gloves (cotton gloves)
- ESD-wristband

### **1.8.3 Instructions**

Disassemble the phone as described in Working Instructions, SP/Mechanical.  
(2004. Disassembly)

Replace the defective component, according to the Spare Part List.

Assemble the phone as described in Working Instructions, SP/Mechanical.  
(2. Reassembly)

## 2 Revision History

Rev.	Date	Changes / Comments
A	2003-10-30	First release
B	2004-03-02	Components L1, L7, C71 added
C	2004-07-28	Component R29, D8, D22 (page 5)
D	2005-09-08	Component Q3 added